


MATERIAL DECLARATION SHEET



Material Number	BIDD05N60T TO-252			
Product Line	Semiconductor			
Compliance Date	2022-05-03			
RoHS Compliant	YES, 7(a)	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Chip1	Silicon	0.00379	Silicon dioxide	14808-60-7	0.91%	0.0057%	1.24%
				Silicon	7440-21-3	79.02%	0.4910%	
				Aluminum	7429-90-5	6.76%	0.0420%	
				Silver	7440-22-4	5.61%	0.0349%	
				Titanium	7440-32-6	0.22%	0.0014%	
				Nickel	7440-02-0	0.43%	0.0027%	
				Silicon nitride	12033-89-5	0.01%	0.0001%	
				TiN	25583-20-4	0.02%	0.0001%	
	Chip2			Copper	7440-50-8	5.84%	0.0363%	
				Vanadium	7440-62-2	1.18%	0.0073%	
				Silicon dioxide	14808-60-7	0.28%	0.0035%	
				Platinum	7440-06-4	0.03%	0.0004%	
				Silicon	7440-21-3	98.88%	1.2287%	
				Aluminum	7429-90-5	0.36%	0.0045%	
				Silver	7440-22-4	0.02%	0.0002%	
				Titanium	7440-32-6	0.24%	0.0030%	
2	Al wire	Aluminum	0.000663	Aluminum	7429-90-5	100.00%	0.2174%	0.22%
				Lead	7439-92-1	95.50%	1.0646%	1.11%
3	Soft Solder	PbSnAg	0.0034	Tin	7440-31-5	2.00%	0.0223%	
				Silver	7440-22-4	2.50%	0.0279%	
				Copper	7440-50-8	99.87%	56.1620%	56.24%
4	Lead frame	Copper	0.171517	Iron	7439-89-6	0.10%	0.0562%	
				Phosphorus	7723-14-0	0.03%	0.0169%	

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5	Mold Compound	Resin	0.12097	Silica, vitreous	60676-86-0	80.00%	31.7298%	39.66%
				Phenol polymer with 1,4-bis(methoxymethyl)benzene	26834-02-6	7.00%	2.7764%	
				Phenol polymer with 3a,4,7,7a-tetrahydro-4,7-methano-1Hindene, glycidyl ether	119345-05-0	7.00%	2.7764%	
				Carbon black	1333-86-4	1.00%	0.3966%	
				Secret	Secret	5.00%	1.9831%	
6	Plating	Matte-100% tin	0.00466	Tin	7440-31-5	100.00%	1.5279%	1.53%
		Total weight	0.305g					

This Document was updated on: 2022/05/03

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements

7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)